

### Features

- High luminous power.
- Green color.
- Bulk, available taped on reel.
- ESD-withstand voltage: up to 4KV
- The product itself will remain within RoHS compliant version.

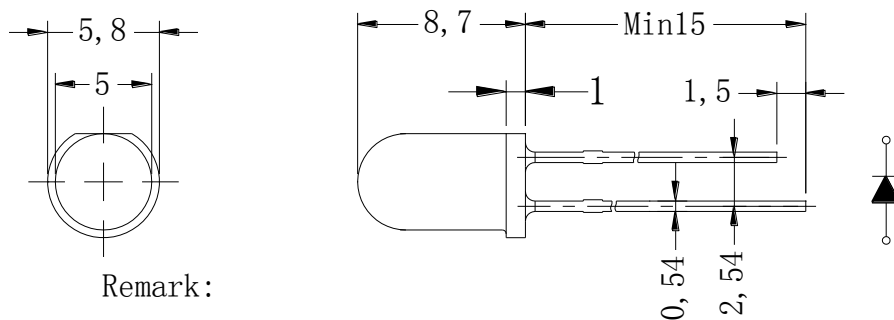
### Descriptions

- The series is designed for application required high luminous intensity.
- The phosphor filled in InGaN chip to ideal white.

### Device Selection Guide

LED Part No.	Chip Material	Lens Color
G5112UC	InGaN	Water clear

### Package Dimensions



Remark:

1. Unit:mm
2. The key DIM tolerance less than +/-0.1mm

### Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Continuous Forward Current	I <sub>F</sub>	20	mA
Peak Forward Current	I <sub>FP</sub>	1	A
Reverse Voltage	V <sub>R</sub>	5	V
Operating Temperature	T <sub>opr</sub>	-40 ~ +85	°C
Storage Temperature	T <sub>stg</sub>	-40 ~ +85	°C
Soldering Temperature	T <sub>sol</sub>	260	°C
Power Dissipation at 25°C Free Air Temperature	P <sub>d</sub>	110	mW
Zener Reverse Current	I <sub>Z</sub>	100	mA

**Notes:** 1:I<sub>FP</sub> Conditions--Pulse Width ≅ 100μs and Duty ≅ 1%.

2:Soldering time ≅ 5 seconds.

### Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
Forward	V <sub>F</sub>	I <sub>F</sub> =20mA	2.8	--	3.4	V
Zener Voltage	V <sub>Z</sub>	I <sub>Z</sub> =5mA	5.2	--	--	V
Reverse Current	I <sub>R</sub>	V <sub>R</sub> =5V	--	--	5	μA
Luminous Intensity	I <sub>v</sub>	I <sub>F</sub> =20mA	8000		10000	mcd
View Angle	2θ <sub>1/2</sub>	I <sub>F</sub> =20mA	--	30	--15	deg
Peak Wavelength	λ <sub>p</sub>	I <sub>F</sub> =20mA	503	--	505	nm

### Packing Quantity Specification

1. 1000PCS/Bag

### Notes

#### 1. Lead Forming

- a) During lead formation, the leads should be bent at a point at least 3mm from the base of the epoxy bulb.
- b) Lead forming should be done before soldering.
- c) Avoid stressing the LED package during leads forming. The stress to the base may damage the LED's characteristics or it may break the LEDs.
- d) Cut the LED leadframes at room temperature. Cutting the leadframes at high temperatures may cause failure of the LEDs.
- e) When mounting the LEDs onto a PCB, the PCB holes must be aligned exactly with the lead position of the LED. If the LEDs are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the LEDs.

#### 2. Storage

- a) The LEDs should be stored at 30°C or less and 70%RH or less after being shipped from Xinghui and the storage life limits are 3 months. If the LEDs are stored for 3 months or more, they can be stored for a year in a sealed container with a nitrogen atmosphere and moisture absorbent material.
- b) Please avoid rapid transitions in ambient temperature, especially, in high humidity environments where condensation can occur.

#### 3. Soldering

- a) Careful attention should be paid during soldering. When soldering, leave more than 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.

b) Recommended soldering conditions:

Hand Soldering		DIP Soldering	
Temp. at tip of iron	300°C Max. (60W Max.)	Preheat temp.	100°C Max. (60 sec Max.)
Soldering time	3 sec Max.	Bath temp. & time	260 Max., 5 sec Max
Distance	3mm Min.(From solder joint to epoxy bulb)	Distance	3mm Min. (From solder joint to epoxy bulb)

### Remark

1. Above specification may be changed without notice. XingHui will reserve authority on material change for above specification.
2. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. XingHui assumes no responsibility for any damage resulting from use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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